

KYOCERA KE-1000SV

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

High Reliable and Easy-to-Use Molding Compounds for Various Type of Packages

Strong Points

Provide Various Molding Compounds with High Reliability to Cover Many Applications such as LSI, Transistors and Diodes.

Good Curability and Applicable to Various Molding Machines (Both Automated and Conventional)

Low Stress of Large chips and Applicable to Encapsulation.

Application

Smaller SOP, Smaller QFP, DIP, SIP/ZIP, TO-PKG, DPAK, SOT, Unbalanced PKG, Module

General Information		
Uses	Electrical/Electronic Applications	
Physical	Nominal Value	Unit
Specific Gravity	1.80	g/cm ³
Spiral Flow	95.0	cm
Mechanical	Nominal Value	Unit
Flexural Modulus	12500	MPa
Flexural Strength	135	MPa
Thermal	Nominal Value	Unit
Glass Transition Temperature	200	°C
CLTE - Flow		
-- 1	1.5E-5	cm/cm/°C
-- 2	5.8E-5	cm/cm/°C
Uncured Properties	Nominal Value	Unit
Gel Time	0.47	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

The information and data on this page are provided by manufacturers and document providers. SHANGHAI SUSHENG assumes no legal liability. It is strongly recommended to verify all technical data with material suppliers before final material selection. All rights belong to the original authors. If any infringement occurs, please contact us immediately.

Recommended distributors for this material

Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519

Phone: +86 13424755533

Email: sales@su-jiao.com

No. 215, Lianhe North Road, Fengxian District, Shanghai, China



WECHAT